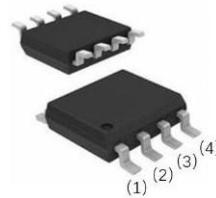
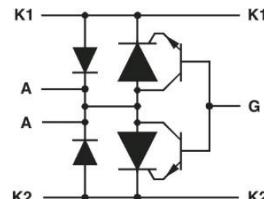


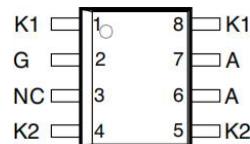
**High Voltage Ringing SLIC Protector**

Waveshape	$I_{PPSM}$
5/320μs	50A
10/1000μs	40A
1.2/50μs	120A

**SOP-8L****Descriptions**

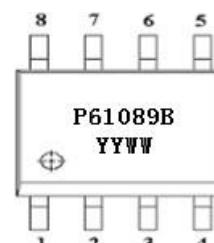
This device is especially designed to protect Subscriber Line Interface Circuit (SLIC) against transient overvoltage.

Positive overloads are clipped with 2 diodes. Negative surges are suppressed by 2 Thyristors, their breakdown voltage being referenced to VBAT through the gate. This component presents a very low gate triggering current and minimizes overvoltage stress on the SLIC.

**Package & Device Symbol****Pin configuration (Top view)****Features**

- Dual programmable transient suppressor
- Wide battery voltage supports
- Low gate triggering current
- High holding current.
- MSL: Level 3

Pin	Pin Name	Description
1, 8	K1	Connect to subscriber lines (Tip/Ring)
4, 5	K2	
2	G	Connect to battery (Reference Voltage)
6, 7	A	Connect to ground
3	NC	Not connected



P61089B = Device Code

Y = Special Code

Y = Year

WW = Week

**Marking****Order information**

Device	Package	Shipping
P61089B	SOP-8L	4000/Reel&Tape

**Applications**

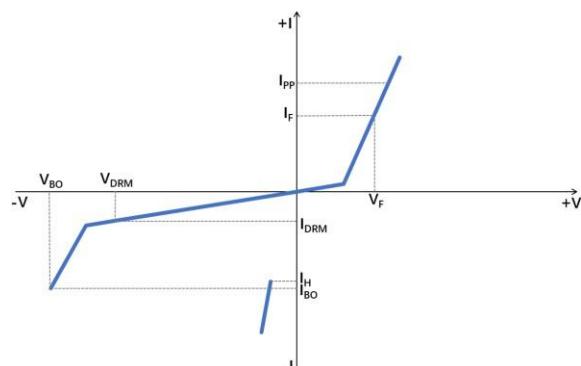
- Switch Line Card
- Access Network Line Card
- PBX
- VoIP

## Absolute Maximum ratings

Parameter		Symbol	Value	Unit
Non-repetitive peak on-state pulse current	10/1000μs (Telcordia (Bellcore) GR-1089-CORE, Issue 2, February 1999, Section 4)	I <sub>PPSM</sub>	40	A
	5/320μs (ITU-T K.20, K.21& K.45, K.44 open-circuit voltage wave shape 10/700 μs)		50	
	1.2/50μs ( Telcordia (Bellcore) GR-1089-CORE, Issue 2, February 1999, Section 4)		120	
Non repetitive peak on-state current (sinusoidal) 60Hz	0.5s	I <sub>TSM</sub>	6.5	A
	1s		4.5	
	5s		2.4	
	30s		1.3	
	900s		0.72	
Repetitive peak off-state voltage, V <sub>GK=0</sub>		V <sub>DRM</sub>	-170	V
Repetitive peak gate-cathode voltage, V <sub>KA=0</sub>		V <sub>GKRM</sub>	-167	V
Operating free-air temperature range		T <sub>A</sub>	-40-85	°C
Storage temperature range		T <sub>STG</sub>	-40-150	°C
Junction temperature		T <sub>J</sub>	-40-150	°C
Maximum lead temperature for soldering during 10s		T <sub>L</sub>	260	°C
Junction to free air thermal resistance		R <sub>θJA</sub>	120	°C /W

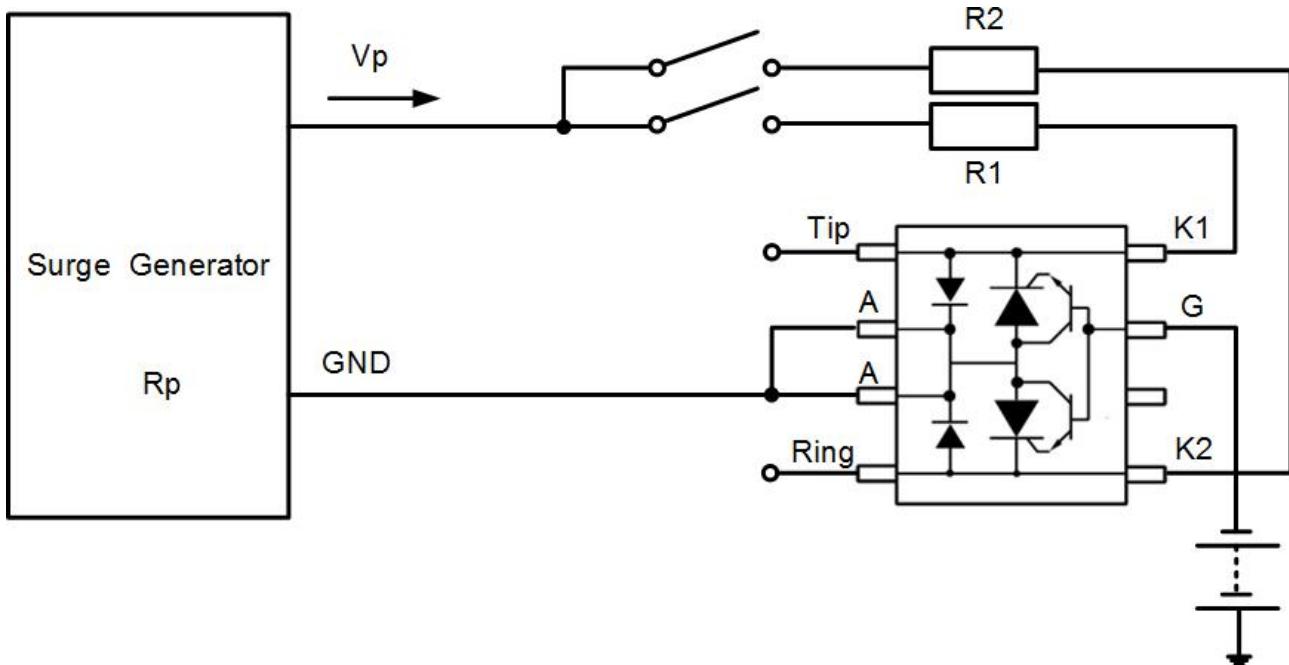
## Parameter Measurement Information

Parameter	Symbol
Off-state current	I <sub>DRM</sub>
Holding current	I <sub>H</sub>
Breakover voltage	V <sub>(BO)</sub>
Forward voltage	V <sub>F</sub>
Peak forward recovery voltage	V <sub>FRM</sub>
Gate-cathode impulse breakover voltage	V <sub>GK(BD)</sub>
Gate reverse current	I <sub>GKS</sub>
Gate trigger current	I <sub>GT</sub>
Gate-cathode trigger voltage	V <sub>GT</sub>
Cathode-anode off-state capacitance	C <sub>KA</sub>



**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

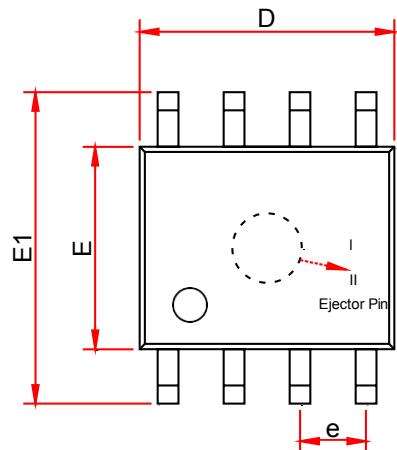
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward voltage	V <sub>F</sub>	I <sub>F</sub> =5A, t <sub>w</sub> =200μs			3	V
Impulse peak forward recovery voltage	V <sub>FRM</sub>	2/10us, I <sub>F</sub> =100A, R <sub>S</sub> =50Ω, di/dt=80A/us			10	V
Off-state current	I <sub>D</sub>	V <sub>D</sub> = -170V, V <sub>GK</sub> =0, T <sub>J</sub> = 25 °C			-5	uA
		V <sub>D</sub> = -170V, V <sub>GK</sub> =0, T <sub>J</sub> = 85 °C				
Impulse breakdown voltage	V <sub>(BO)</sub>	2/10us, I <sub>TM</sub> =100A, R <sub>S</sub> =50Ω di/dt=-80A/us, V <sub>GG</sub> =-100V			-112	V
Holding current	I <sub>H</sub>	I <sub>T</sub> =-1A, di/dt=1A/ms, V <sub>GG</sub> =-100V	-150			mA
Gate reverse current	I <sub>GAS</sub>	V <sub>GG</sub> =V <sub>GK</sub> = -167V, V <sub>KA</sub> =0, T <sub>J</sub> = 25 °C			-5	uA
		V <sub>GG</sub> =V <sub>GK</sub> = -167V, V <sub>KA</sub> =0, T <sub>J</sub> = 85 °C				
Gate trigger current	I <sub>GT</sub>	V <sub>AK</sub> =40V, Value=3.5V, t <sub>w</sub> =10ms			5	mA
Gate trigger voltage	V <sub>GT</sub>	V <sub>AK</sub> =40V, Value=3.5V, t <sub>w</sub> =10ms			2.5	V
Anode-cathode offstate capacitance	C <sub>KA</sub>	f=1MHz, V <sub>D</sub> =1V, I <sub>G</sub> =0, V <sub>D</sub> =-3V			110	pF
		f=1MHz, V <sub>D</sub> =1V, I <sub>G</sub> =0, V <sub>D</sub> =-48V			55	

**Surge Test Circuit**


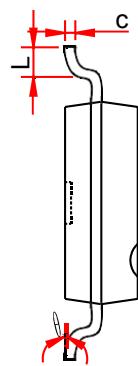
Pulse(μs)		Vp(V)	Ipp(A)	Rp(Ω)	R1(Ω)	R2(Ω)
T <sub>rise</sub>	T <sub>fall</sub>					
10	700	±2000	±50	40	0	0
10	1000	±400	±40	10	0	0
1.2	50	±5000	±120	2	40	40

## Package Outline Dimensions

SOP-8L



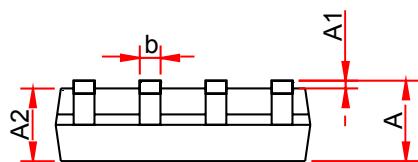
TOP VIEW



I) NA

II) (C)

SIDE VIEW

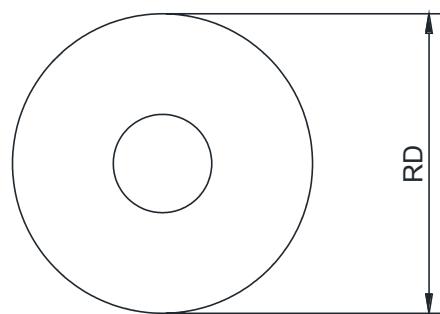


SIDE VIEW

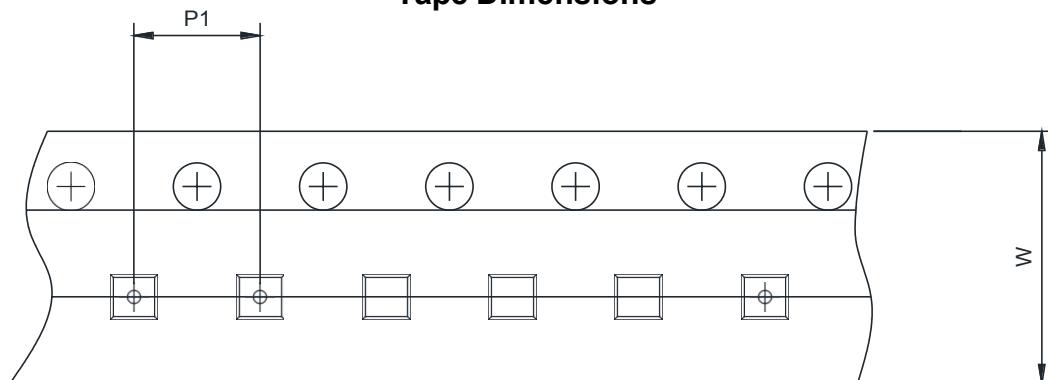
Symbol	Dimensions In Millimeters (mm)		
	Min.	Typ.	Max.
A	1.35	1.55	1.75
A1	0.05	0.15	0.25
A2	1.25	1.40	1.65
b	0.33	-	0.51
c	0.15	-	0.26
D	4.70	4.90	5.10
E	3.70	3.90	4.10
E1	5.80	6.00	6.20
e	1.27BSC		
L	0.40	-	1.27
θ	0°	-	8°

## Tape and Reel Information

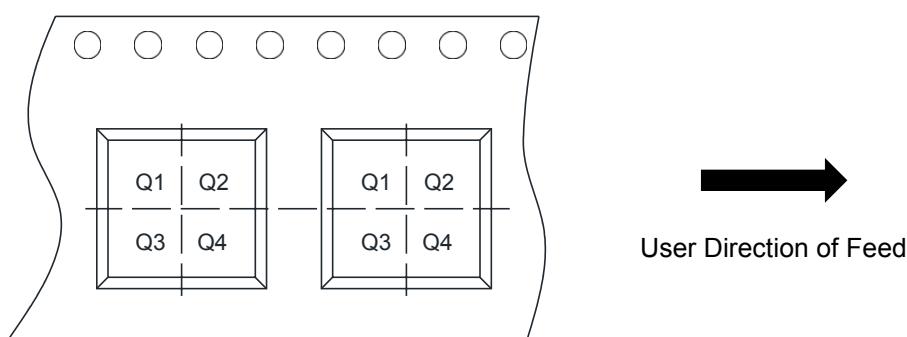
### Reel Dimensions



### Tape Dimensions



### Quadrant Assignments For PIN1 Orientation In Tape



RD	Reel Dimension	<input type="checkbox"/> 7inch <input checked="" type="checkbox"/> 13inch
W	Overall width of the carrier tape	<input type="checkbox"/> 8mm <input checked="" type="checkbox"/> 12mm
P1	Pitch between successive cavity centers	<input type="checkbox"/> 2mm <input type="checkbox"/> 4mm <input checked="" type="checkbox"/> 8mm
Pin1	Pin1 Quadrant	<input checked="" type="checkbox"/> Q1 <input type="checkbox"/> Q2 <input type="checkbox"/> Q3 <input type="checkbox"/> Q4